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Re; Docket No: YOR920030098US1
Serial No: 10/729,254

Comments:

Response with election attached

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of : March 2, 2006
D. C. Edelstein, et al : Group Art No.: 2826
Serial No. 10/729,254 : Examiner: A. O. Williams
Filed: December 5, 2003 : for IBM Corporation
Anne Vachon Dougherty
3173 Cedar Road
Yorktown Hts, NY 10598
Title: SILICON CHIP CARRIER
WITH CONDUCTIVE THROUGH-VIAS
AND METHOD FOR FABRICATING SAME

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents

Sir:

In response to the Requirement for Restriction dated
February 3, 2006, Applicants aver the following:

Claims 26-42 of the original parent application have been
withdrawn from prosecution;

Applicants assert that Claim 1 is generic and that the
species of the claimed invention include:

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Species 1, figures 2A, 2B and 2C covered by sub-genus Claim 7 which recites the semiconductor carrier structure of Claim 1 wherein said each conductive structure comprises a first conductive via material disposed in annular shape along the sidewalls of said through-via and having a core structure comprising a second via material. Under the sub-genus Claim 7 are the species having variations of the core structure which include the following:

Species 1(a), figure 2A having a first conductive annular ring and an inner core structure of one different material, covered by generic Claim 1, sub-genus Claim 7, and species Claims 8-14;

Species 1(b), figure 2B having a first conductive annular ring and an inner core structure comprising a sealed void, covered by generic Claim 1, sub-genus Claim 7, and species Claim 15;

Species 1(c), figure 2C having a first conductive annular ring and an inner core structure comprising more than one ring, covered by generic Claim 1, sub-genus Claim 7, and a no other species claims at this time;

Species 2, figure 2D wherein there is one via fill material, covered by generic Claim 1 and species Claims 2-6 and 16-19.

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Applicants note that Claims 20-25 depend from Claim 1, but recite structural features which can be used with any one of the species;

Applicants elect to prosecute Claims 1-26;

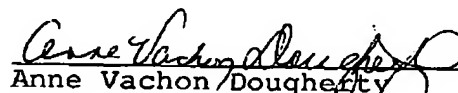
Should the generic claim fall, Applicants provisionally elect to prosecute Species 1, the sub-genus covered by Claim 7 and Claims 8-15; and

Should the sub-genus claim fall, Applicants provisionally elect to prosecute Species 1(a), the species covered by Claims 8-14.

Applicants point out that a Continuation-in-Part (CIP) application has been filed for the above-identified patent application (serial number 11/242,221). The undersigned attorney placed a telephone call to Examiner Williams to determine if the Restriction Requirement would be withdrawn in view of the filing of the CIP application. Since the requirement has not been withdrawn, Applicants are filing this Response.

Respectfully submitted,
D. Edelstein, et al

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